

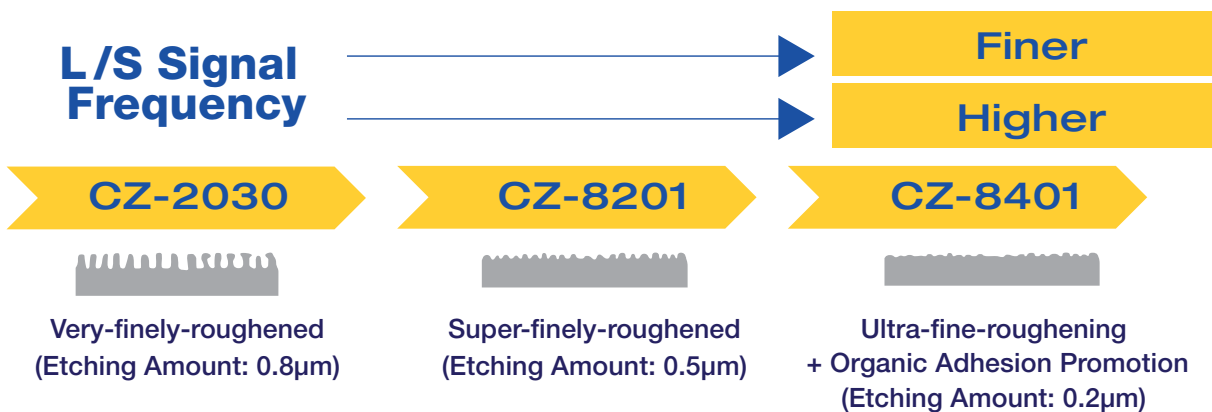


Global Leader in Final Finish Technologies

- **TWX-42 RAIG** (Reduction-Assisted Immersion Gold) deposits 6-8 μm gold with zero nickel corrosion.
- **Talon 3** electroless palladium: the foundation for ENEPIG, EPIG and EPAG final finish layer deposits
- **TPD-23** electroless pure palladium for ENEPIG and wire bond applications
- **Direct Immersion Gold** for dense, non-porous deposits up to 0.3 μm ; meets highest standards for HF and fine pattern compatibility

MEC from Uyemura Provides Industry's Roadmap for High Density and Ultra High Density Circuits

Etchbond optimizes copper bonding to resin, dry film or solder mask.



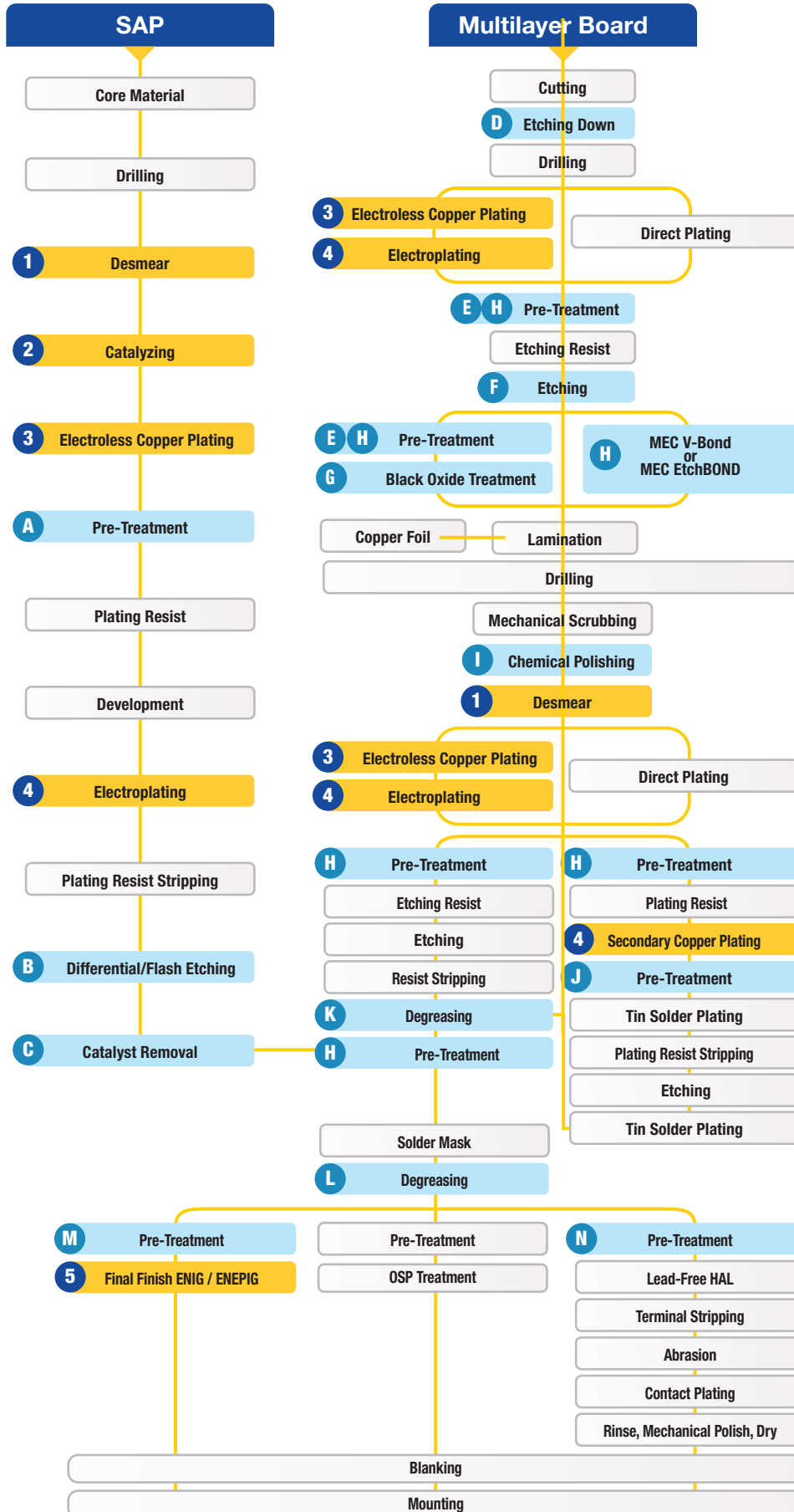
V-BOND 7710 is an $\text{H}_2\text{SO}_4\text{-H}_2\text{O}_2$ -type microetchant with substantial cost and maintenance advantages compared with conventional oxide alternatives. It provides exceptional inner layer adhesion to all resins, including high Tg, HF (halogen-free), and PTFE.

Anisotropic Etching Enhancers including EXE-6722, improve sidewall profiles and enable finer lines and higher yields.

Flash and Differential Etchants for SAP/mSAP provide precise controlled etching and optimize sidewall geometries.



MEC from Uyemura IC Substrate Process Chart



Index

UYEMURA PRODUCTS

- 1 APPDES
- 2 ALCUP™
- 3 PEA
- 4 THRU-CUP™
- 5 MPC/MFD5/TALON/NPR/TWX

MEC PRODUCTS

- A STZ-3100 or STL
- B QE-7330, CI-7200
- C PJ-9720
- D HE-7002A
- E CB-5002
- F EXE SERIES
- G V-BOND BO-7710V
- H CZ-2030, CZ-2050, or CZ-8201 (with CL-8300 or CL-2301)
- I SF-5420
- J CA-91Y, CB-801Y, CB-5620AY, or CA-5342
- K CA-5372 or CA-5342
- L CA-5342
- M CA-5330K or CA-5344
- N CZ-5480



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